



FIS920040114US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re patent application of

Hsu et al.

Serial No.: 10/710,880

Group Art Unit: Not Yet Assigned

Filing Date: 08-10-04

Examiner: Unknown

For: PARTIAL WAFER BONDING AND DICING

Commissioner of Patents
PO Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

Under the provisions of 37 CFR §1.97 through §1.99 and pursuant to applicants' duty of disclosure under 37 CFR §1.56, applicants respectfully bring the following documents, listed on the attached form PTO-1449, to the attention of the Examiner in charge of the above-identified application. This citation does not constitute an admission that the references are relevant or material to the claims. They are only cited as constituting related art of which the applicants are aware.

It is respectfully requested that the listed references be considered by the Examiner and formally made of record in this application.

Please charge any deficiencies in fees and credit any overpayment of fees to Attorney's Deposit Account No. 09-0458.

Respectfully submitted,

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INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)				ATTY DOCKET NO. FIS920040114US1		APPLICATION NO. 10/710,880		
				Hsu et al.				
				FILING Concurrently Herewith		GROUP ART Unknown		
PATENT & TRADEMARK OFFICE								
U.S. PATENT DOCUMENTS								
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
U.S. PATENT APPLICATION PUBLICATIONS								
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
		WO9925019	05/20/99	International				
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)								
		K. Gann, "High Density Packaging of Flash Memory", IEEE, 1998, pp. 96-98.						
		V. Dragoi et al., "Reversible Wafer Bonding For Reliable Compound Semiconductor Processing", IEEE, 2002, pp. 331-334.						
EXAMINER					DATE CONSIDERED			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)	ATTY DOCKET NO. FIS920040114US1	APPLICATION NO. 101710,880.
	Hsu et al.	
	FILING Concurrently Herewith	GROUP ART Unknown

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

U.S. PATENT APPLICATION PUBLICATIONS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

			G. Reed, "Semiconductor Packaging", Semiconductor International, September, 2003, pp. 50.

EXAMINER	DATE CONSIDERED
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